Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	265	(438/67).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/01/13 12:49
L2	169	(438/68).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/01/13 11:38
L3	1222	(438/107).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/01/13 11:38
L4	1466	(438/108).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/01/13 12:07
L5	444	(438/110).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/01/13 11:38
L6	978	(438/113).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/01/13 11:38
L7	23430	jang.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 12:43
L8	9	7 and se-young	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 12:19
L9	12	(("20020089067") or ("20030038342") or ("20030045028") or ("5710071") or ("6201301") or ("6507119")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/01/13 12:19
L10	114572	park.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 12:38
L11	83	min-young.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 12:38

L12	34650	hong.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 12:43
L13	0	12 and soo-min	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 12:43
L14	0	12 and (soo-min)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 12:44
L15	5	12 and (soon-min)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 12:44
L16	3931	(438/67,68,107,108,110,113). CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/01/13 12:51
L17	38	16 and wafer with (flip adj chip) and ((encapsulant$4 or underfill$4) with (harden or hardening or cure or curing)) and (chip or die) and (cut or cutting or sever$5 or separat$5) and @ad<="20040413"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 14:58
L18	2	("20030116347").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/01/13 14:07
L19	253	(((semiconductor adj package) or (semiconductor adj wafer))) and solder and (resin or underfill or encapsulant) and (hardening or harden or curing or cure) and (severing or severe or cut or cutting or separat$5) and (heat adj treat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 14:13
L20	131	(semiconductor adj wafer) and solder and (resin or underfill or encapsulant) and (hardening or harden or curing or cure) and (severing or severe or cut or cutting or separat$5) and (heat adj treat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 14:26

L21	1	((semiconductor adj wafer) with (mount$4 adj solder)) and (resin or underfill or encapsulant) and (hardening or harden or curing or cure) and (severing or severe or cut or cutting or separat$5) and (heat adj treat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 14:16
L22	21	((semiconductor adj wafer) with (solder)) and (resin or underfill or encapsulant) and (hardening or harden or curing or cure) and (severing or severe or cut or cutting or separat$5) and (heat adj treat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 14:25
L23	3	((semiconductor adj wafer) near (solder)) and (resin or underfill or encapsulant) and (hardening or harden or curing or cure) and (severing or severe or cut or cutting or separat$5) and (heat adj treat$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 14:25
L24	41	16 and (wafer with (solder adj bump) and ((resin or encapsulant$4 or underfill$4) with (harden or hardening or cure or curing)) and (cut or cutting or sever$5 or separat$5)) and @ad<="20040413"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/13 15:01
L25	2	("6194788" | "6207475").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/13 15:14
L26	2	("6881607").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/01/13 15:14
L27	14	("4812949" | "5019944" | "5389182" | "5668404" | "5672548" | "5766982" | "5785799" | "5793099" | "5834790" | "5872051" | "5960260" | "5970320" | "5981315" | "6197616").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/13 15:21